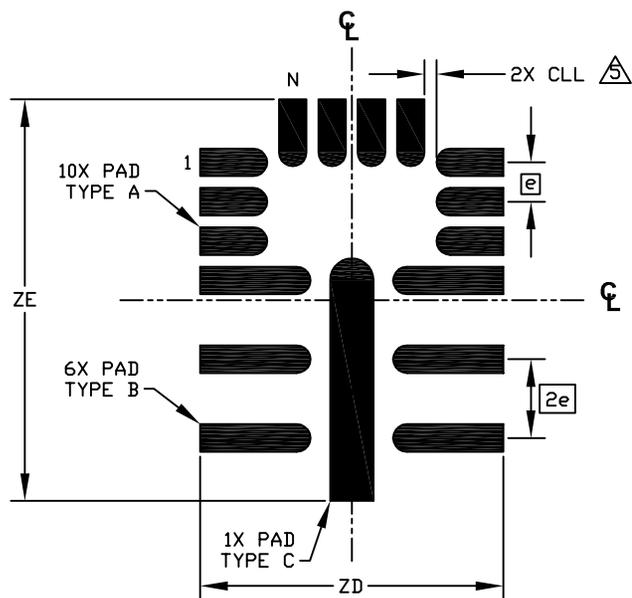
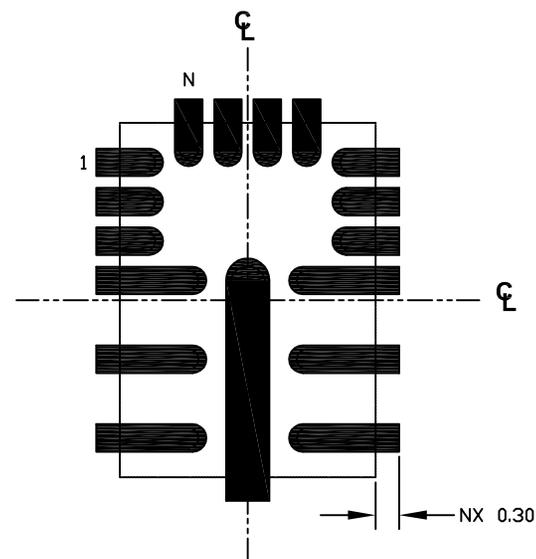


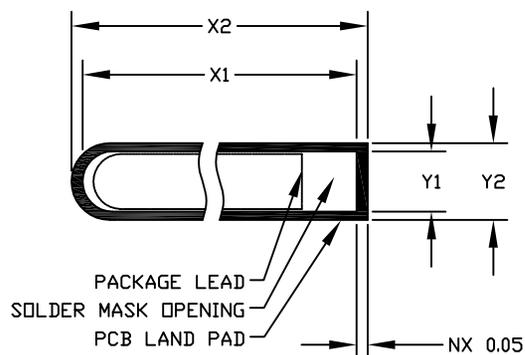
RECOMMENDED LAND PATTERN



PACKAGE OVERLAY



PAD DETAIL INFORMATION



DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
CLL		0.15 REF			.006 REF	
e		0.50 BSC			.020 BSC	
N		17 PINS			17 PINS	
ZD		3.85 REF			.152 REF	
ZE		5.10 REF			.201 REF	

DIM	MILLIMETERS			INCHES		
	TYPE A	TYPE B	TYPE C	TYPE A	TYPE B	TYPE C
Y1	0.28	0.28	0.48	.011	.011	.019
Y2	0.35	0.35	0.55	.014	.014	.022
X1	0.75	1.30	2.98	.030	.051	.117
X2	0.85	1.40	3.08	.033	.055	.121

NOTES:

1. REFERENCE PKG. OUTLINE: 21-0991
 2. LAND PATTERN COMPLIES TO: IPC7351A.
 3. ALL DIMENSIONS APPLY TO PbFREE (+) PKG. CODE ONLY.
 4. ALL DIMENSIONS IN MM.
- △ CLL IS THE CORNER PAD EDGE TO ADJACENT INSIDE PAD DISTANCE.

-DRAWING NOT TO SCALE-



TITLE:
PACKAGE LAND PATTERN,
[P173A4F+1] FCQFN

APPROVAL

DOCUMENT CONTROL NO.
90-0495

REV. A

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This document (including dimensions, notes & specs) is a recommendation based on typical circuit board manufacturing parameters. Since land pattern design depend on many factors unknown to Maxim (eg. user's board manufacturing specs), user must determine suitability for use. This document is subject to change without notice. Contact technical support at <http://www.maximintegrated.com/support> for further questions.